

157 Series – Standard Nano²® Fuse and Clip Assembly



Description

The 157 Series – Standard Nano Fuse/Clip assembly is a small, square, very fast acting surface mount fuse that is assembled in surface mountable fuse clips. The fuse clip and pre-installed fuse combination can be automatically placed in PC Board in one efficient manufacturing operation. It permits quick and easy replacement of fuses without performing desoldering process, even in the field and without exposing the PC Board to detrimental effects of rework solder heat.

Features

- Surface Mountable, Very Fast Acting Fuse.
- Easily replaceable on PC Board (Field Replaceable)
- Fully compatible with RoHS/Pb-Free solder alloys and higher temperature profiles associated with leadfree assembly.
- RoHS compliant and Halogen Free
- Available in ratings of 0.062 ~ 10 Amperes.

Agency Approvals

| AGENCY | AGENCY FILE NUMBER | AMPERE RANGE |
|--------|---|------------------------------------|
| | E14721 | 0.062A ~ 10A |
| | NBK030205-E10480A NBK030205-E10480B NBK101105-E184655 | 1A - 1.6A 2A - 5A 6.3A - 10A |

Electrical Characteristics for Series

| % of Ampere Rating | Opening Time at 25°C |
|--------------------|----------------------|
| 100% | 4 hours Minimum |
| 200% | 5 secs. Maximum |

Applications

- Instrumentation
- Telecommunications
- Base Stations

Electrical Specifications by Item

| Ampere Rating (A) | Amp Code | Max Voltage Rating (V) | Interrupting Rating (A) | Fuse Furnished | Nominal Cold Resistance (Ohms) | Nominal Melting I ² t (A ² sec) | Agency Approvals | |
|-------------------|----------|------------------------|--|----------------|--------------------------------|---|------------------|---|
| | | | | | | | | |
| 0.062 | .062 | 125 | 50A @ 125 VAC/VDC 300A @ 32 VDC | 0451.062 | 5.5372 | 0.00019 | X | |
| 0.080 | .080 | 125 | | 0451.080 | 4.0500 | 0.00033 | X | |
| 0.100 | .100 | 125 | | 0451.100 | 3.1000 | 0.00138 | X | |
| 0.125 | .125 | 125 | | 0451.125 | 1.7059 | 0.00286 | X | |
| 0.160 | .160 | 125 | | 0453.160 | 1.2157 | 0.0048 | X | |
| 0.200 | .200 | 125 | | 0453.200 | 1.3971 | 0.00652 | X | |
| 0.250 | .250 | 125 | | 0453.250 | 1.0496 | 0.01126 | X | |
| 0.315 | .315 | 125 | | 0453.315 | 0.3881 | 0.0311 | X | |
| 0.375 | .375 | 125 | | 0453.375 | 0.6100 | 0.0442 | X | |
| 0.400 | .400 | 125 | | 0453.400 | 0.5600 | 0.0551 | X | |
| 0.500 | .500 | 125 | | 0453.500 | 0.4200 | 0.0824 | X | |
| 0.630 | .630 | 125 | | 0453.630 | 0.3050 | 0.1381 | X | |
| 0.750 | .750 | 125 | | 0453.750 | 0.2450 | 0.2143 | X | |
| 0.800 | .800 | 125 | | 0453.800 | 0.2120 | 0.2654 | X | |
| 1.0 | 001. | 125 | | 0453001. | 0.1530 | 0.6029 | X | X |
| 1.25 | 1.25 | 125 | | 04531.25 | 0.078 | 0.664 | X | X |
| 1.5 | 01.5 | 125 | | 045301.5 | 0.0634 | 0.853 | X | X |
| 1.6 | 01.6 | 125 | | 045301.6 | 0.0580 | 1.060 | X | X |
| 2.0 | 002. | 125 | | 0453002. | 0.0373 | 0.530 | X | X |
| 2.5 | 02.5 | 125 | | 045302.5 | 0.0288 | 1.029 | X | X |
| 3.0 | 003. | 125 | | 0453003. | 0.0229 | 1.650 | X | X |
| 3.15 | 3.15 | 125 | | 04533.15 | 0.0215 | 1.920 | X | X |
| 3.5 | 03.5 | 125 | | 045303.5 | 0.0203 | 2.469 | X | X |
| 4.0 | 004. | 125 | | 0453004. | 0.0163 | 3.152 | X | X |
| 5.0 | 005. | 125 | | 0453005. | 0.0127 | 5.566 | X | X |
| 6.3 | 06.3 | 125 | | 045306.3 | 0.0098 | 9.17 | X | X |
| 7.0 | 007. | 125 | | 0453007. | 0.0092 | 10.32 | X | X |
| 8.0 | 008. | 125 | | 0453008. | 0.0079 | 20.23 | X | X |
| 10.0 | 010. | 125 | 35A @ 125 VAC / 50A @125 VDC 300A @ 32VDC | 0453010. | 0.0058 | 26.46 | X | X |

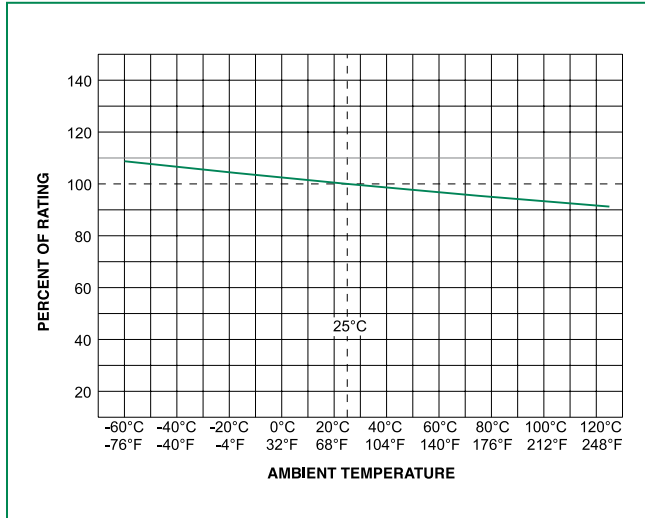
1. Cold resistance measured at less than 10% of rated current at 23°C.

2. I²t values stated for 8ms opening time.

3. Agency Approval Table Key: X=Approved or Certified, P=Pending and Blank=Not Approved

4. Have special electrical characteristic needs? Contact Littelfuse to learn more about application specific options.

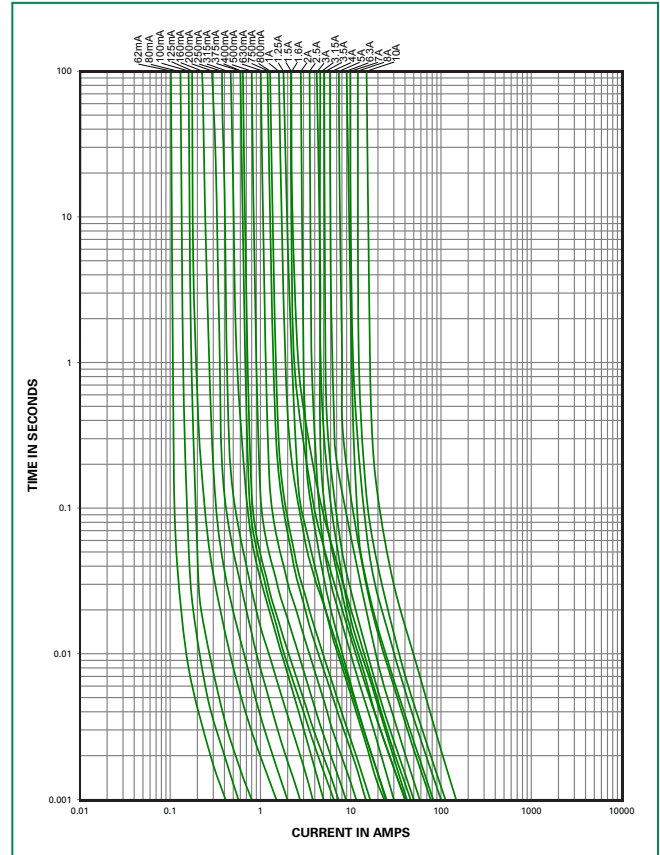
Temperature Re-rating Curve



Note:

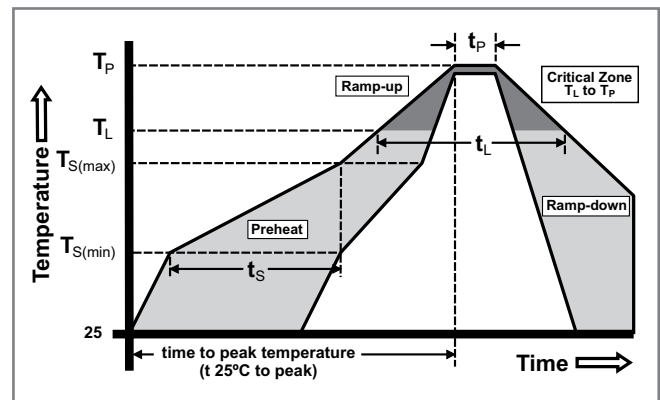
1. Re-rating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Average Time Current Curves



Soldering Parameters

| | | |
|--|------------------------------------|-------------------------|
| Reflow Condition | | Pb – Free assembly |
| Pre Heat | - Temperature Min ($T_{s(min)}$) | 150°C |
| | - Temperature Max ($T_{s(max)}$) | 200°C |
| | - Time (Min to Max) (t_s) | 60 – 120 secs |
| Average ramp up rate (Liquidus Temp (T_L) to peak) | | 5°C/second max. |
| $T_{s(max)}$ to T_L - Ramp-up Rate | | 5°C/second max. |
| Reflow | - Temperature (T_L) (Liquidus) | 217°C |
| | - Temperature (t_l) | 60 – 90 seconds |
| Peak Temperature (T_p) | | 260 ^{+0/-5} °C |
| Time within 5°C of actual peak Temperature (t_p) | | 20 – 40 seconds |
| Ramp-down Rate | | 5°C/second max. |
| Time 25°C to peak Temperature (T_p) | | 8 minutes max. |
| Do not exceed | | 260°C |

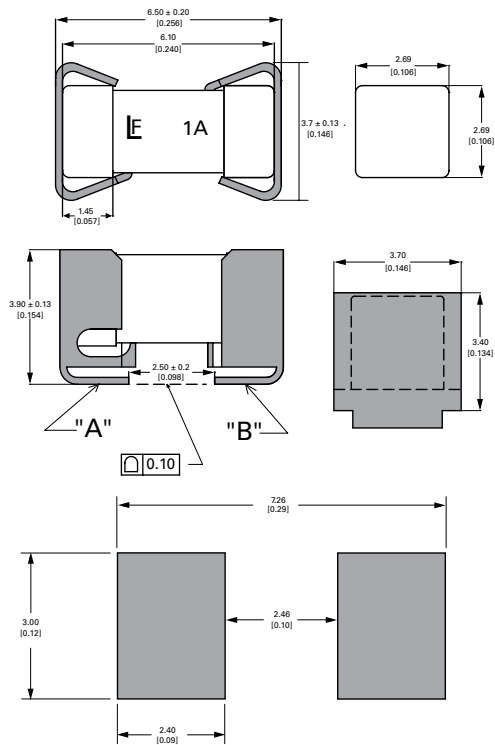


Product Characteristics

| | |
|-------------------------------|---|
| Materials | Body: Ceramic Cap: For 0.062A ~ 0.125A – Au plated Brass For 0.200A ~ 10A – Silver plated Brass Clip Plating: Matte Tin |
| Product Marking | Body: Brand Logo, Current Rating |
| Clip Retention | Force applied at fuse center, perpendicular to the long axis (@ 0.75 lbs. MIN) |
| Solderability | MIL-STD-202, Method 208 / IPC/ EIA / JEDEC J-STD-002, Test Condition A |
| Humidity Test | MIL –STD-202, Method 103 @ 85°C / 85%RH, 1000 hours |
| Resistance to Solvents | MIL-STD-202, Method 215 (3 solvent types) |

| | |
|-------------------------------|--|
| Operating Temperature | -55°C to 125°C with proper derating |
| Thermal Shock | MIL-STD-202, Method 107, Test Condition B (5 cycles -65°C to +125°C) |
| Vibration | MIL-STD-202, Method 201 (10-55 Hz) |
| Moisture Resistance | MIL-STD-202, Method 106, 10 cycles |
| Salt Spray/ Atmosphere | MIL-STD-202, Method 101, Test Condition B (48 hrs.), 5% NaCl in De-ionized Water |
| Shock | MIL-STD-202, Method 213, Test Condition I (100 G's peak for 6 milliseconds) |

Dimensions



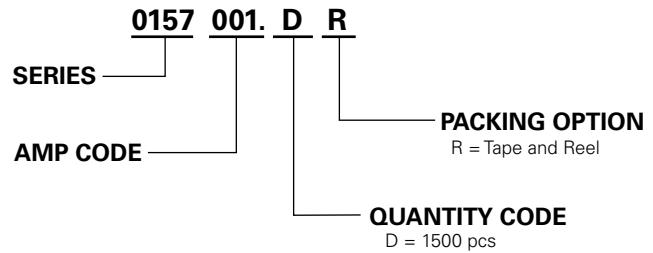
PCB Recommendation for Thermal Management

1. Minimum Copper Layer Thickness = 100um
2. Minimum Copper Trace Width = 10mm

Note:

Alternate methods of thermal management may be used. In such cases, under normal operations, the maximum temperature of the fuse body should not exceed 80°C in a 25°C ambient environment.

Part Numbering System



Packaging

| Packaging Option | Packaging Specification | Quantity | Quantity & Packaging Code |
|------------------|-------------------------|----------|---------------------------|
| Tape and Reel | Surface Mount | 1500 | DR |

Additional Information



Datasheet



Resources



Samples

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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